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September 2016

## FDV045P20L

## P-Channel PowerTrench® MOSFET -20 V, -1.15 A, 108 mΩ

#### **Features**

- Max  $r_{DS(on)}$  = 108 m $\Omega$  at  $V_{GS}$  = -4.5 V,  $I_D$  = -1.15 A
- Max  $r_{DS(on)}$  = 121 m $\Omega$  at  $V_{GS}$  = -2.5 V,  $I_D$  = -0.7 A
- Very low r<sub>DS(on)</sub> Mid Voltage P-channel Silicon Technology Optimised for Low Qg
- This product is optimised for fast switching applications as well as load switch applications

D

**SOT-23** 

- 100% UIL Tested
- RoHS Compliant

#### **General Description**

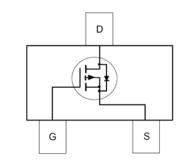
This P-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench® process that has been optimized for the on-state resistance and yet maintain superior switching performance.

### **Applications**

- Active Clamp Switch
- Load Switch







## **MOSFET Maximum Ratings** $T_A = 25$ °C unless otherwise noted.

Symbol	Parameter		Ratings	Units
V <sub>DS</sub>	Drain to Source Voltage		-20	V
V <sub>GS</sub>	Gate to Source Voltage		±8	V
1	-Continuous	(Note 1a)	-1.15	۸
ID	-Pulsed	(Note 4)	-33	_ A
E <sub>AS</sub>	Single Pulse Avalanche Energy	(Note 3)	13	mJ
D	Power Dissipation	(Note 1a)	1.6	W
$P_{D}$	Power Dissipation	(Note 1b)	0.7	VV
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Range		-55 to +150	°C

#### **Thermal Characteristics**

$R_{\thetaJA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	80	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1b)	180	C/VV

#### **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDV045P20L	FDV045P20L	SOT-23	7 "	8 mm	3000 units

## **Electrical Characteristics** $T_J = 25$ °C unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Chara	cteristics					
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	$I_D = -250 \mu A, V_{GS} = 0 V$	-20			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	$I_D$ = -250 $\mu$ A, referenced to 25 °C		-18		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = -16 V, V <sub>GS</sub> = 0 V			-1	μΑ
I <sub>GSS</sub>	Gate to Source Leakage Current	$V_{GS} = \pm 8 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA

#### On Characteristics (Note 2)

V <sub>GS(th)</sub>	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = -250 \mu A$	-0.5	-0.9	-1.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D$ = -250 $\mu$ A, referenced to 25 °C		3		mV/°C
	V <sub>GS</sub> = -4.5 V, I <sub>D</sub> = -1.15 A		86	108		
	r <sub>DS(on)</sub> Static Drain to Source On Resistance	$V_{GS} = -2.5 \text{ V}, I_D = -0.7 \text{ A}$		97	121	
r <sub>DS(on)</sub>		$V_{GS} = -1.8 \text{ V}, I_D = -0.5 \text{ A}$		121	160	mΩ
		$V_{GS} = -4.5 \text{ V}, I_D = -1.15 \text{A},$ $T_J = 125 \text{ °C}$		110	138	
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = -5 V, I <sub>D</sub> = -1.15 A		3		S

#### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance		812	1220	pF
C <sub>oss</sub>	Output Capacitance	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1  MHz	119	167	рF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 - 1 1011 12	108	151	pF
$R_{g}$	Gate Resistance		20		Ω

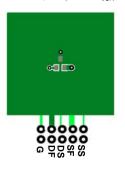
#### **Switching Characteristics**

t <sub>d(on)</sub>	Turn-On Delay Time			8.4	17	ns
t <sub>r</sub>	Rise Time	V <sub>DD</sub> = -10 V, I <sub>D</sub> = -1.15 A,		6.5	13	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS}$ = -4.5 V, $R_{GEN}$ = 6 $\Omega$		76	122	ns
t <sub>f</sub>	Fall Time			26	42	ns
$Q_g$	Total Gate Charge	V <sub>GS</sub> = 0 V to -4.5 V		7.2	10	nC
Qg	Total Gate Charge	$V_{GS} = 0 \text{ V to -2.5 V}$ $V_{DD}$	=-10 V,	4.4	6.2	nC
Q <sub>gs</sub>	Gate to Source Gate Charge	I <sub>D</sub> =	-1.15A	1.2		nC
$Q_{gd}$	Gate to Drain "Miller" Charge			1.8		nC

#### **Drain-Source Diode Characteristics**

$V_{SD}$	Source to Drain Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = -1.15 A (Note 2)		-0.8	-1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> = -1.15 A, di/dt = 100 A/μs		11	20	ns
Q <sub>rr</sub>	Reverse Recovery Charge			2	10	nC

Notes: 1.  $R_{\theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta CA}$  is determined by the user's board design.



a) 80 °C/W when mounted on a 1 in² pad of 2 oz copper



b) 180 °C/W when mounted on a minimum pad.

- 2. Pulse Test: Pulse Width < 300  $\mu$ s, Duty cycle < 2.0%. 3. Starting T<sub>J</sub> = 25 °C; P-ch: L = 3 mH, I<sub>AS</sub> = -3 A, V<sub>DD</sub> = -20 V, V<sub>GS</sub> = -6.4 V. 4. Pulsed Id refer to Fig 10 SOA curve for more details.

## **Typical Characteristics** $T_J = 25$ °C unless otherwise noted.

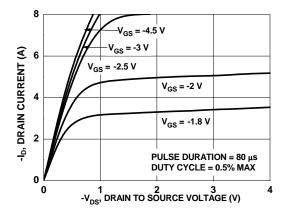


Figure 1. On Region Characteristics

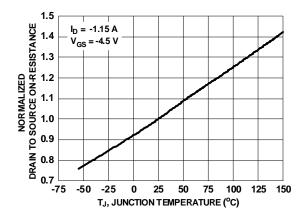


Figure 3. Normalized On Resistance vs. Junction Temperature

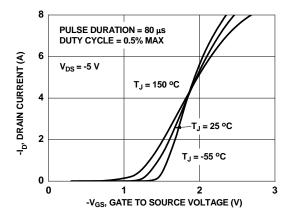


Figure 5. Transfer Characteristics

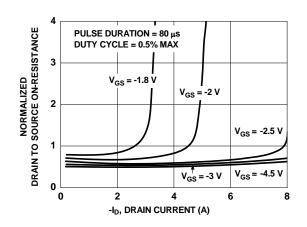


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

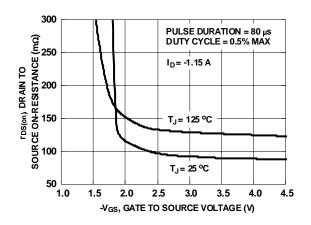


Figure 4. On-Resistance vs. Gate to Source Voltage

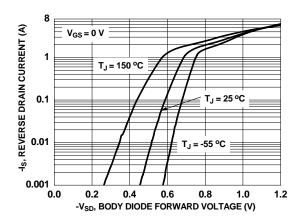


Figure 6. Source to Drain Diode Forward Voltage vs. Source Current

## **Typical Characteristics** $T_J = 25$ °C unless otherwise noted.

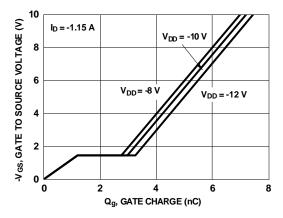


Figure 7. Gate Charge Characteristics

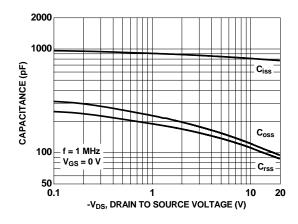


Figure 8. Capacitance vs. Drain to Source Voltage

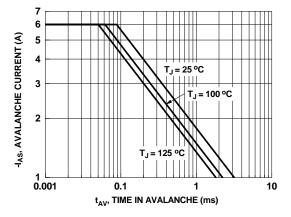


Figure 9. Unclamped Inductive Switching Capability

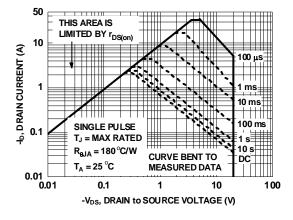


Figure 10. Forward Bias Safe Operating Area

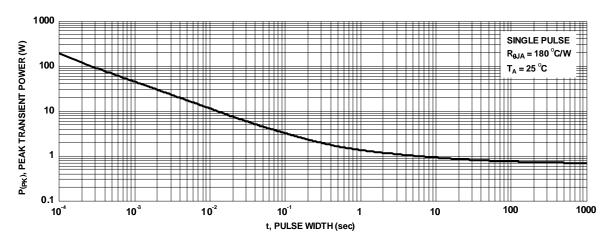


Figure 11. Single Pulse Maximum Power Dissipation

## Typical Characteristics $T_J = 25 \, ^{\circ}\text{C}$ unless otherwise noted.

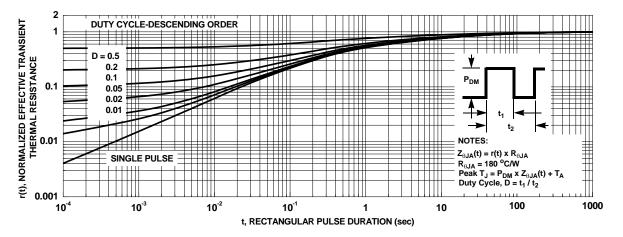


Figure 12. Junction-to-Ambient Transient Thermal Response Curve





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